



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-10-19
Contact Name *	Refer to Supplier comment section	Contact Title	Refer to Supplier comment section
Authorized Representative *	FLORIANA SAN BIAGIO	Representative Title	AMS Material Declaration Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
IIS2DHTR	22BB*HK01AFA	A	MA1A	2015-10-19
	Amount	UoM	Unit type	ST ECOPACK Grade
	8.5	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Gold (Ni/Au), electrolytic	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
LGA	2x2x1	12	No lead	
Comment	Package: A0K6 VFLGA 2X2X1 12LD PITCH 0.5MM			

QueryList : ROHS directive 2011/65/EU _ANNEX IV	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description
7c-1	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	22BB*HK01AFA									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Dies	Other inorganic materials	2.921	mg	supplier	die	Silicon (Si)	7440-21-3		2.707	mg	926737	318471				
				supplier	metallisation	Aluminium (Al)	7429-90-5		0.004	mg	1369	471				
				supplier	metallisation	Copper (Cu)	7440-50-8		0.017	mg	5820	2000				
				supplier	metallisation	Tantalum (Ta)	7440-25-7		0.003	mg	1027	353				
				supplier	metallisation	Titanium (Ti)	7440-32-6		0.002	mg	685	235				
				supplier	Passivation	Silicon Nitride (SiN)	12033-89-5		0.006	mg	2054	706				
				supplier	passivation	Silicon Oxide	7631-86-9		0.032	mg	10955	3765				
				JIG - R	die glass coating	Lead-Borate Glass	65997-18-4	7c-I-Electrical and electron	0.150	mg	51352	17647				
				substrate	Other inorganic materials	1.892	mg	supplier	core material	Fiber glass	65997-17-3		0.374	mg	197722	44000
								supplier	core material	Brominated flame retardant	Proprietary		0.018	mg	9516	2118
supplier	core material	epoxy resin	Proprietary						0.488	mg	257991	57412				
supplier	Solder mask	Barium sulfate	7727-43-7						0.014	mg	7401	1647				
supplier	Solder mask	Acrylic resin	9003-01-4						0.021	mg	11102	2471				
supplier	Solder mask	Epoxy resin	29690-82-2						0.017	mg	8987	2000				
supplier	Solder mask	Biphenyl epoxy resin	85954-11-6						0.010	mg	5287	1176				
supplier	Solder mask	Talc containing no asbestiform fibers	14807-96-6						0.008	mg	4229	941				
supplier	Solder mask	Methoxymethylethoxy propanol	34590-94-8						0.002	mg	1057	235				
supplier	Solder mask	Amorphous silica	7631-86-9						0.002	mg	1057	235				
supplier	Solder mask	β-methyl-methoxy-buthyl	103429-90-9						0.001	mg	529	118				
supplier	Solder mask	Silica Cristobalite	14464-46-1						0.001	mg	529	118				
supplier	metallisation	Copper (Cu)	7440-50-8						0.926	mg	489548	108941				
supplier	metallisation	Nickel (Ni)	7440-02-0						0.008	mg	4441	988				
supplier	metallisation	Gold (Au)	7440-57-5						0.001	mg	603	134				
Die attach	Other Organic Materials	0.081	mg					supplier	tape	epoxy resin	Proprietary		0.051	mg	629630	6000
				supplier	tape	polyolefin	9003-07-0		0.026	mg	320988	3059				
				supplier	tape	Diphenol Propane Diglycidyl Ether	1675-54-3		0.004	mg	49383	471				
Bonding wire	Precious metals	0.188	mg	supplier	wire	Gold (Au)	7440-57-5		0.186	mg	989362	21882				
				supplier	wire	Palladium (Pd)	7440-05-3		0.002	mg	10638	235				
encapsulation	Other Organic Materials	3.428	mg	supplier	mold compound	Silica, vitreous	60676-86-0		2.967	mg	865519	349059				
				supplier	mold compound	Epoxy Resin	85954-11-6		0.137	mg	39965	16118				
				supplier	mold compound	Phenol Resin	26834-02-6		0.137	mg	39965	16118				
				supplier	mold compound	Epoxyde Bisphenol A Resin	25068-38-6		0.103	mg	30047	12118				
				supplier	mold compound	Aluminium hydroxyde	21645-51-2		0.069	mg	20128	8118				
supplier	mold compound	Carbon black	1333-86-4		0.015	mg	4376	1765								